



Title of Change:	FDMS86200DC Final Test UIL Condition Change.	
Effective date:	December 19, 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or < ramilangelo.nonato@onsemi.com >	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change Category:	<input type="checkbox"/> Wafer Fab <input type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Semiconductor – Cebu	External Foundry/Subcon Sites: None
Description and Purpose:		
The Product Bulletin is to inform the customer on the change in FDMS86200DC Final Test UIL condition from the current 42A/0.1mH to 31A/0.3mH as a result of the product robustness optimization.		
List of Affected Part:		
FDMS86200DC		